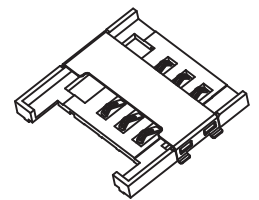
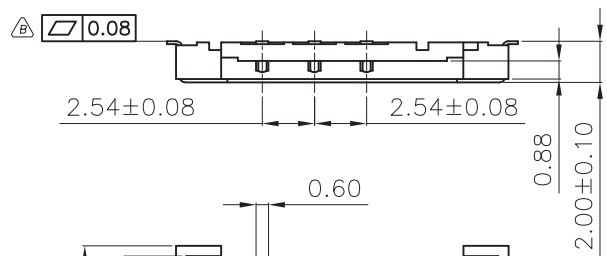
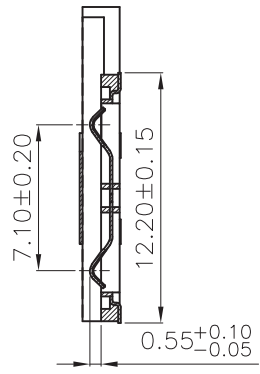
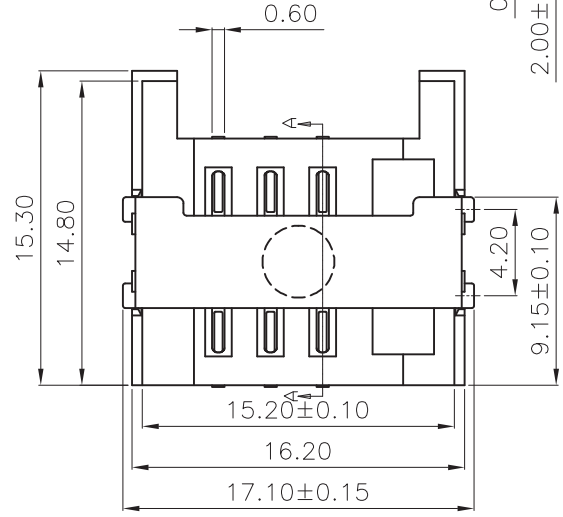


REV.	DESCRIPTION	DATE
B	20101227	Dec 27, 2010



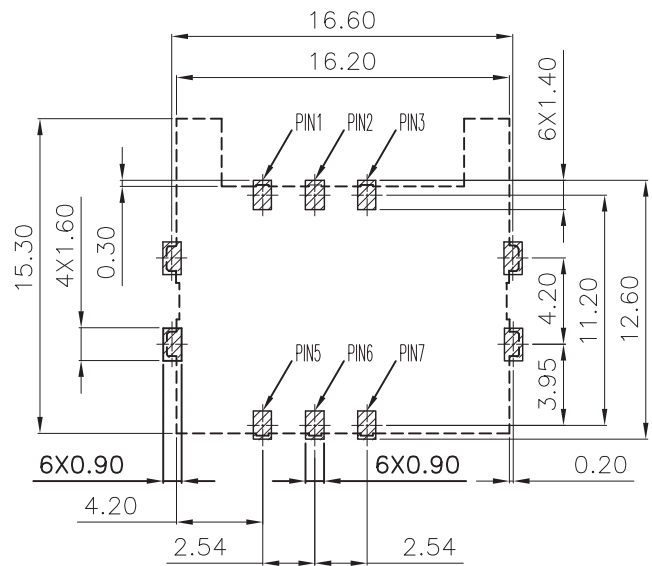
- NOTES:
- MATERIAL:  
I/M: HIGH TEMPERATURE THERMOPLASTIC+COPPER ALLOY  
HOOK: COPPER ALLOY
  - MECHANICAL PERFORMANCE  
CONTACT NORMAL FORCE: 20-50 gf PET PIN AT WORKING POS (HEIGHT=0.15)  
LIFE: 1,500 CYCLES MIN.
  - ELECTRICAL PERFORMANCE  
CONTACT RESISTANCE<PER CONTACT>: 100m MAX  
INSULATION RESISTANCE: 100V DC, 1000M  
CURRENT RATING : 1.0A.  
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC MAX.  
VOLTAGE RATING<SELV>: 15V DC MAX.
  - OPERATING TEMPERATURE RANGE: -25°C TO +85°C.
  - STORAGE TEMPERATURE RANGE: -25°C TO +60°C.
  - COPLANARITY OF HOOK AND CONTACT SOLDERING SURFACE : 0.10
  - HARMFUL MATERIAL CONTROL PLEASE FOLLOW DDC. 'EP112'.
  - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY P DETAILS & AVAILABILITY.
  - DIMENSIONS MARKED \* SHOULD BE CHECKED BY Q.C. AND



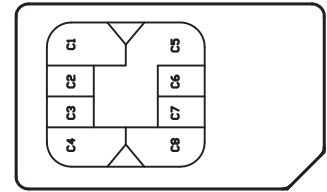
SECTION A:A

ORDER INFORMATION:  
5190106-XC1-X

SERIES CODE: R:ROHS, H:HALOGEN FREE  
SMT: FOLLOW NUMBER  
SMI CARD: CONTACT PLATING:  
SINGLE TYPE: 0: GOLD FLASH  
NUMBER OF POSITIONS: 1: 5u" GOLD, 3: 15u" GOLD



RECOMMENDED P.C.B. LAYOUT TOP VIEW  
TOLERANCE:±0.05



PIN ASSIGNMENT

SIM CARD PIN NO.	PIN NAME	SIM CARD PIN NO.
PIN1	VCC	PIN1
PIN2	RESET	PIN2
PIN3	CLK	PIN3
PIN4		
PIN5	GND	PIN5
PIN6	VPP	PIN6
PIN7	I/O	PIN7
PIN8		

2	I/M	1	COPPER ALLOY + HIGH TEMPERATURE THERMOPLASTIC	NI UNDERPLATING OVER ALL, GOLD FLASH ON MATING AREA AND SOLDER AREA
1	HOOK	1	COPPER ALLOY	NI UNDERPLATING OVER ALL, GOLD FLASH ON SOLDER AREA
ITEM	PART NAME	QTY	MATERIAL	FINISH
TOLERANCE			DRAWER	汉硕电子科技有限公司 SIM CARD SOCKET DRAW NO. R5190106-XC1-X
.0=±0.15			CHECK	
.00=±0.10			APP'D	
.000=±0.05			PRODUCT SPEC.	
ANG.=±3°			UNITS : mm [inch]	
SCALE NONE		SIZE A4	SHEET 1 OF 1	REV. B